

共模扼流滤波器

DC Common Mode (Line Filter)



特性

Characteristics

薄型仅2.50毫米

Low profile only 2.50 mm

高阻抗高达5,000Ω

High impedance up to 5,000 Ω

高达700毫安的大电流

High current up to 700 Ma

应用

Application

数据线和信号线的电流补偿扼流圈

Current compensated choke for data and signal lines

信号和传感器线路、电源系统

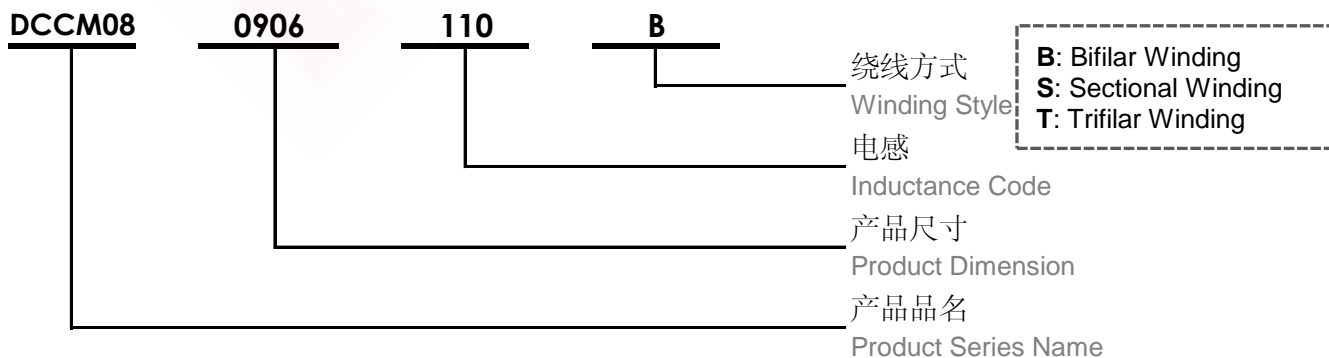
Signal and sensor lines, Power supply system

共模噪声的抑制

Suppression of common mode noise

产品品名介绍

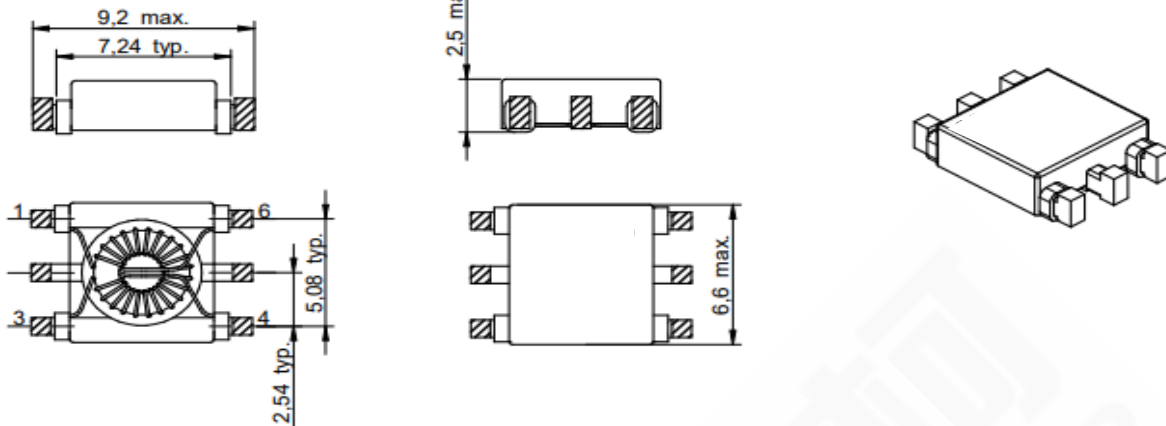
Product Number Structure





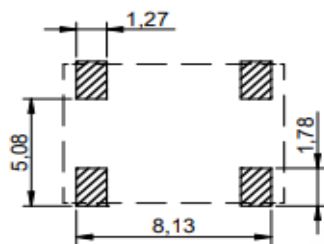
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	电感 Inductance μH	阻抗 Impedance Zmax (Ω)	温升电流 Rated Current I _r max 40°C (mA)	直流电阻 DC Resistance DCR _{max} (Ω)	绕线方式 Winding Style	包装数量 Packaging Qty pcs
DCCM08-0907-220B	22 +50%/-30%	1,600	700	0.14	Bifilar	1,500
DCCM08-0907-510B	51 +50%/-30%	3,300	500	0.25	Bifilar	1,500
DCCM08-0907-101B	100 +50%/-30%	5,000	500	0.28	Bifilar	1,500

测试状态

Test Condition

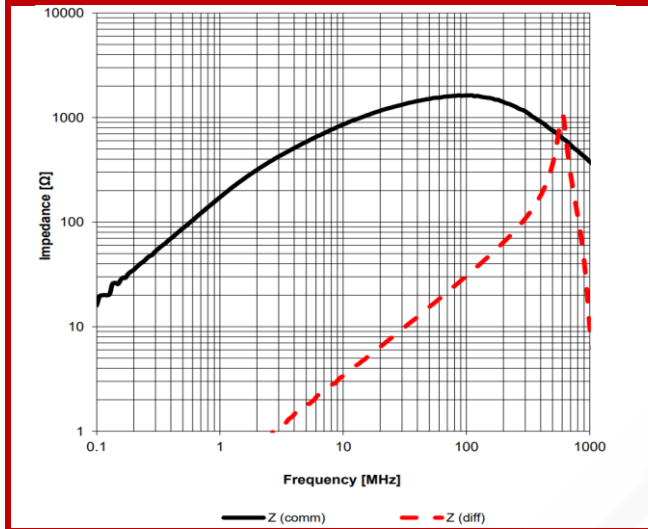
- ☆ 电感测试条件为 100kHz / 100mV (25°C)
Inductance measure condition at 100kHz / 100mV (25°C)
- ☆ 工作温度: -40°C ~ +125°C
Operating Temperature: -40°C ~ +125°C
- ☆ 速率电压: 80V
Rated Voltage: 80V



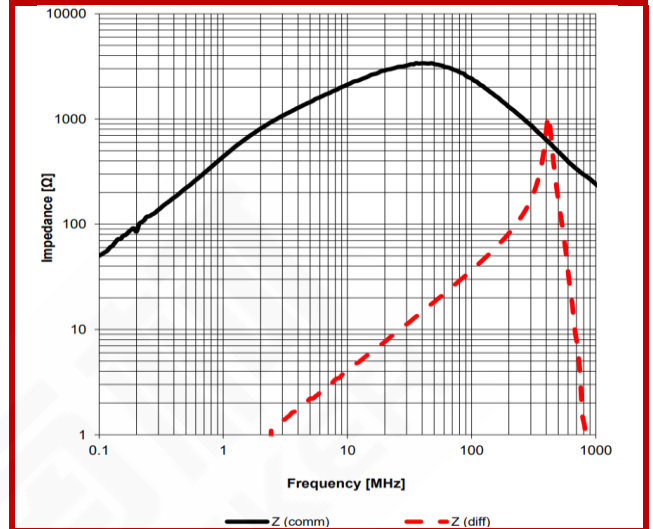
典型阻抗特性

Typical Impedance Characteristics

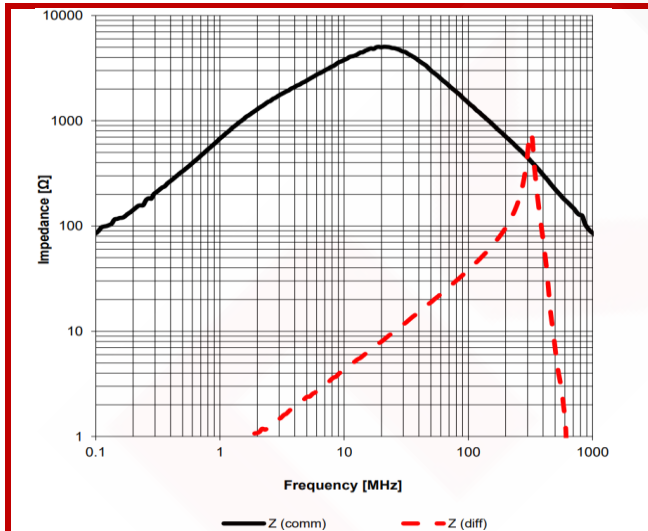
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DCCM08-0907-510B



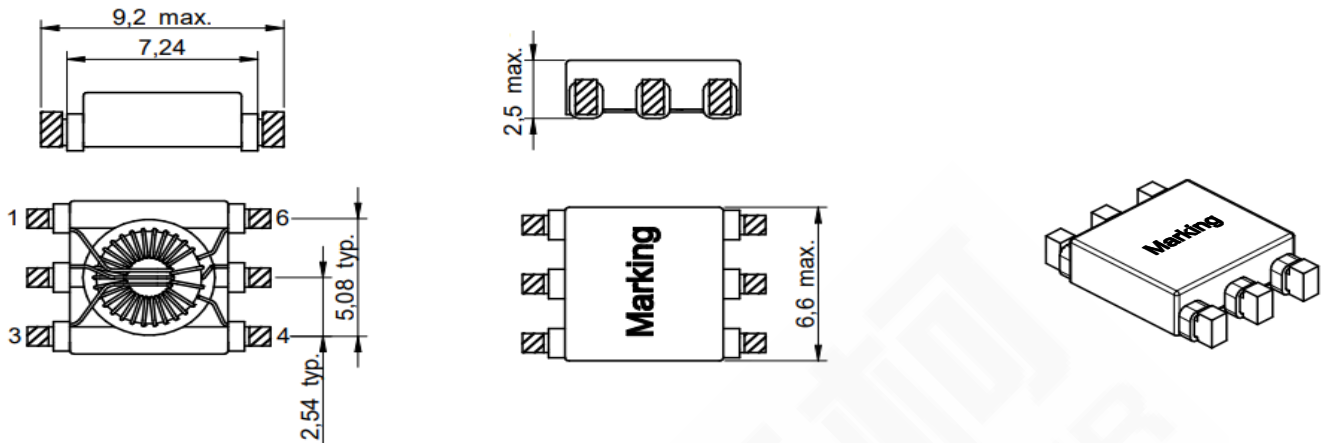
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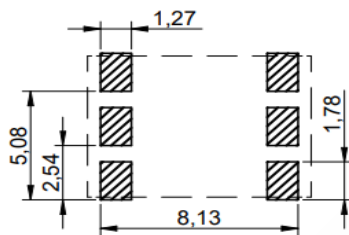
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	电感 Inductance μH	阻抗 Impedance $Z_{\text{max}} (\Omega)$	温升电流 Rated Current $I_r \text{ max } 40^\circ\text{C} (\text{mA})$	直流电阻 DC Resistance $\text{DCR}_{\text{max}} (\Omega)$	绕线方式 Winding Style	包装数量 Packaging Qty pcs
DCCM08-0907-200T	20 +50%/-30%	1,250	500	0.16	Trifilar	1,500
DCCM08-0907-101T	100 +50%/-30%	5,000	450	0.45	Trifilar	1,500

测试状态

Test Condition

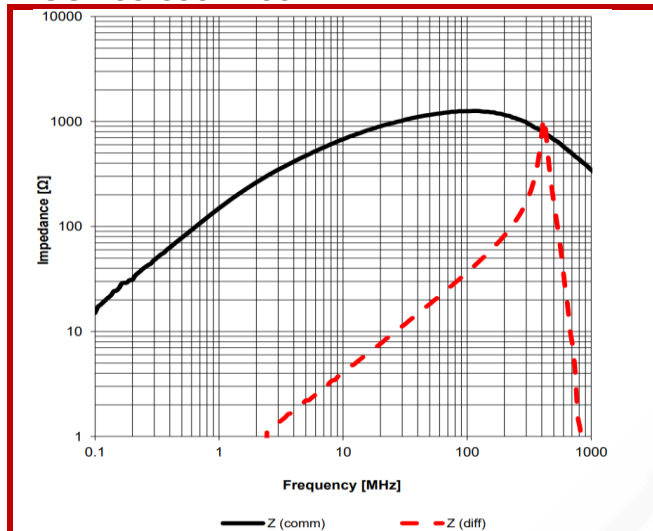
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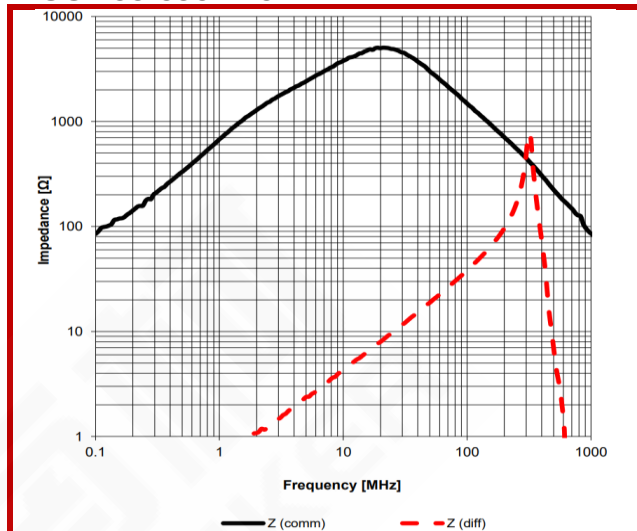
典型阻抗特性

Typical Impedance Characteristics

DCCM08-0907-200T



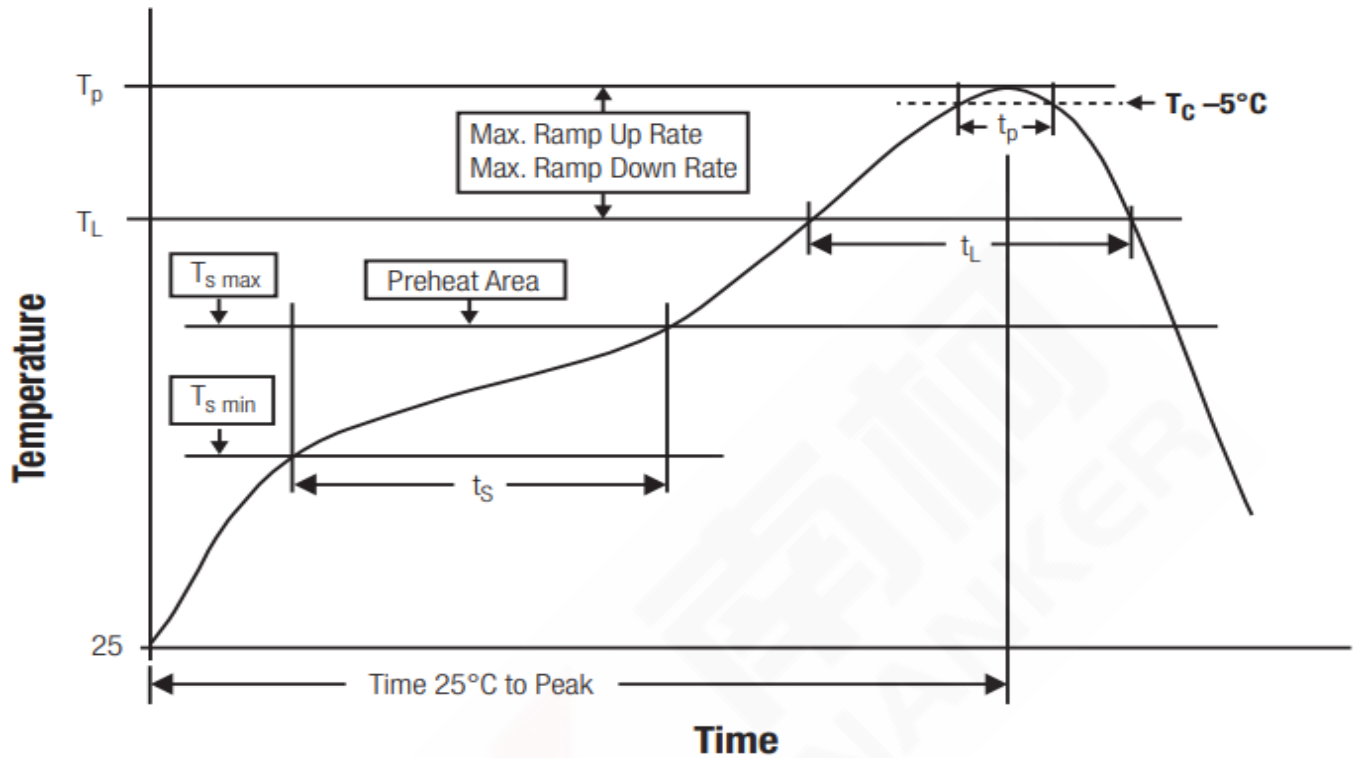
DCCM08-0907-101T





回流焊曲线图

Classification Reflow Profile for SMT Components



封装体峰值温度(Tp)分类

Classification Reflow Soldering Profile:

	封装厚度 Package Thickness	封装体积 Package Volume		
		<350 mm ³	350~2,000 mm ³	>2,000 mm ³
无铅装配 PB-Free Assembly	<1.60mm	260°C	260°C	260°C
	1.60~2.50mm	260°C	250°C	245°C
	>2.50mm	260°C	245°C	245°C

- ◆ 回流焊参照标准 IPC/JEDEC J-STD-020D。
Reflow is refer to standard IPC/JEDEC J-STD-020D.